

Publication list

Until 2015.9, 7 book chapters, 3 standards, 37 journal papers, 59 conference papers, 35 patents.

Thesis

- [1] **C.-A. Yuan**, "Investigation of nano-scaled structural mechanics using the clustered atomistic-continuum method," PhD Thesis, Dep. of Power mechanics, National Tsing Hua University, Hsinchu, Taiwan, 2005.

Book Chapters (7)

- [1] O. Van der Sluis, **C. Yuan**, W. van Driel, and G. Zhang, "Advances in delamination modeling," in *Nanopackaging: Nanotechnologies and Electronics Packaging*, J. E. Morris, Ed., Springer US, 2008, pp. 61-91.
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- [4] S. Koh, W. D. van Driel, **C. A. Yuan**, and G. Q. Zhang, "Degradation Mechanisms in LED Packages," in *Solid State Lighting Reliability*. vol. 1, W. D. van Driel and X. J. Fan, Eds., Springer New York, 2013, pp. 185-205.
- [5] W. D. van Driel, F. E. Evertz, J. J. M. Zaal, O. M. Nıpoles, and **C. A. Yuan**, "An Introduction to System Reliability for Solid-State Lighting," in *Solid State Lighting Reliability*. vol. 1, W. D. van Driel and X. J. Fan, Eds., Springer New York, 2013, pp. 329-346.
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Standards (3)

- [1] 袁长安, 许绍伟, 李博, 阮军, 张国旗, 樊学军等., "Accelerating depreciation test method for LED lighting products," No. CSA020-2013, Beijing: CSAS, 2013.
- [2] 黄杰, 彭浩, 刘东月, 张国旗, 樊学军, 袁长安等, "LED照明产品检验试验规范 第一部分: 通用要求" No. CSA019.1-2013, Beijing: CSAS, 2013.
- [3] 张国旗, 袁长安, 樊学军, 钱诚, 孙博, 罗长春等, "室外LED照明产品用LED模块直流或交流电子控制装置加速试验方法," No. CSA029-2015, Beijing: CSAS, 2015.

Journal Papers (37)

- [1] K.-N. Chiang and **C.-A. Yuan**, "An overview of solder bump shape prediction algorithms with validations," *IEEE Trans. Adv. Packag.*, vol. 24, pp. 158-162, 2001.
- [2] **C.-A. Yuan** and K.-N. Chiang, "Micro to Macro Thermo-Mechanical Simulation of Wafer Level Packaging," *J. Electron. Packag.*, vol. 125, pp. 576-581, 2003.
- [3] **C. Yuan** and K. Chiang, "Investigation of dsDNA stretching meso-mechanics using LS-DYNA," *FEA information worldwide news (e-journal)*, vol. 11, pp. 61 - 68, 2004.
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- [37] **C.A. Yuan**, "The extended Beer-Lambert Theory for Ray Tracing Modeling of LED Chip-scaled Packaging Application With Multiple Luminescence Materials," *Optical Materials*, vol

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Conference Papers (59)

- [1] **C.-A. Yuan**, C. N. Han, and K.-N. Chiang, "Design and analysis of novel glass WLCSP structure," in *Proc. 5th International Conference on Thermal and Mechanical Simulation and Experiments in Microelectronics and Microsystems (EuroSimE)*, Brussels, Belgium, 2004, pp. 279-285.
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